

FDC5612

60V N-Channel PowerTrench™ MOSFET

General Description

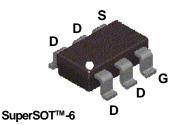
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

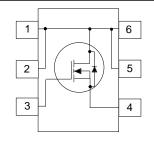
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\rm DS(ON)}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

Features

- 4.3 A, 60 V. $R_{DS(ON)} = 0.055 \text{ W} @ V_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 0.064 \text{ W} @ V_{GS} = 6 \text{ V}.$
- Low gate charge (12.5nC typical).
- Fast switching speed.
- $\bullet \;\;$ High performance trench technology for extremely low $R_{\scriptscriptstyle DS(ON)}.$
- SuperSOT™-6 package: small footprint (72% smaller than standard SO-8); low profile (1mm thick).





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V _{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		<u>±</u> 20	V
I _D	Drain Current - Continuous	(Note 1a)	4.3	Α
	Drain Current - Pulsed		20	
P _D	Power Dissipation for Single Operation	(Note 1a)	1.6	W
		(Note 1b)	0.8	
T _J , T _{stq}	Operating and Storage Junction Temperatu	-55 to +150	∘C	

Thermal Characteristics

$R_{\theta^{JA}}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	∘C/W
R _{OJC}	Thermal Resistance, Junction-to-Case	(Note 1)	30	∘C/W

Package Outlines and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity	
.612	FDC5612	7"	8mm	3000 units	

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Symbol	Parameter	Test Conditions	Test Conditions Min			
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60			V
ΔBVDSS ΔTJ	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25°C		58		mV/∘C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	2.2	4	V
$\frac{\Delta VGS(th)}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-5.5		mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}, T_J = 125 ^{\circ}\text{C}$ $V_{GS} = 6 \text{ V}, I_D = 4 \text{ A}$		0.042 0.072 0.048	0.055 0.094 0.064	Ω
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	10			Α
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 4.3 \text{ A}$		14		S
Dvnamio	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		650		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		80		pF
C _{rss}	Reverse Transfer Capacitance			35		pF
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_D = 1 \text{ A},$		11	20	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		8	18	ns
t _{d(off)}	Turn-Off Delay Time			19	35	ns
t _f	Turn-Off Fall Time			6	15	ns
Q_g	Total Gate Charge	$V_{DS} = 30 \text{ V}, I_{D} = 4.3 \text{ A},$		12.5	18	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		2.4		nC
Q_{gd}	Gate-Drain Charge			2.6		nC
Drain-So	ource Diode Characteristics and	d Maximum Ratings				
I _s	Maximum Continuous Drain-Source Dic				1.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	I — —			V	

Notes:

^{1.} R_{qJA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{qJC} is guaranteed by design while R_{qCA} is determined by the user's board design.

a) 78 °C/W when mounted on a 1.0 in² pad of 2 oz. copper.

b) 156 °C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width £ 300 ms, Duty Cycle £ 2.0%

Typical Characteristics

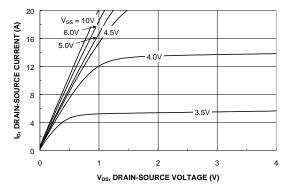


Figure 1. On-Region Characteristics.

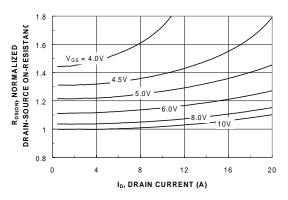


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

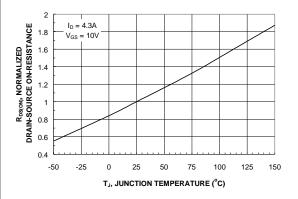


Figure 3. On-Resistance Variation with Temperature.

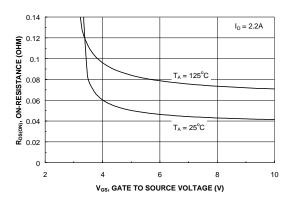


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

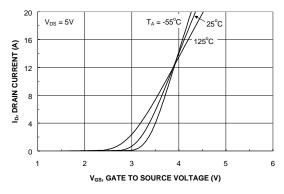


Figure 5. Transfer Characteristics.

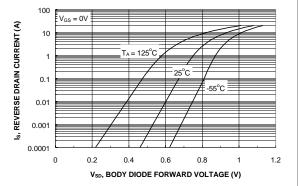
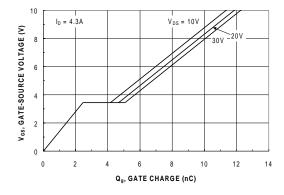


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



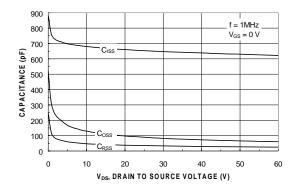
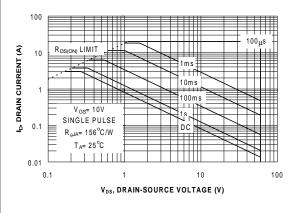


Figure 7. Gate-Charge Characteristics.

Figure 8. Capacitance Characteristics.



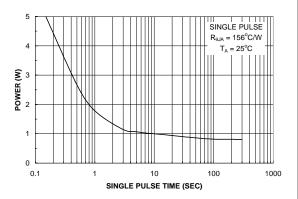


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

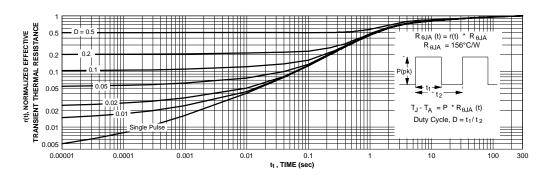
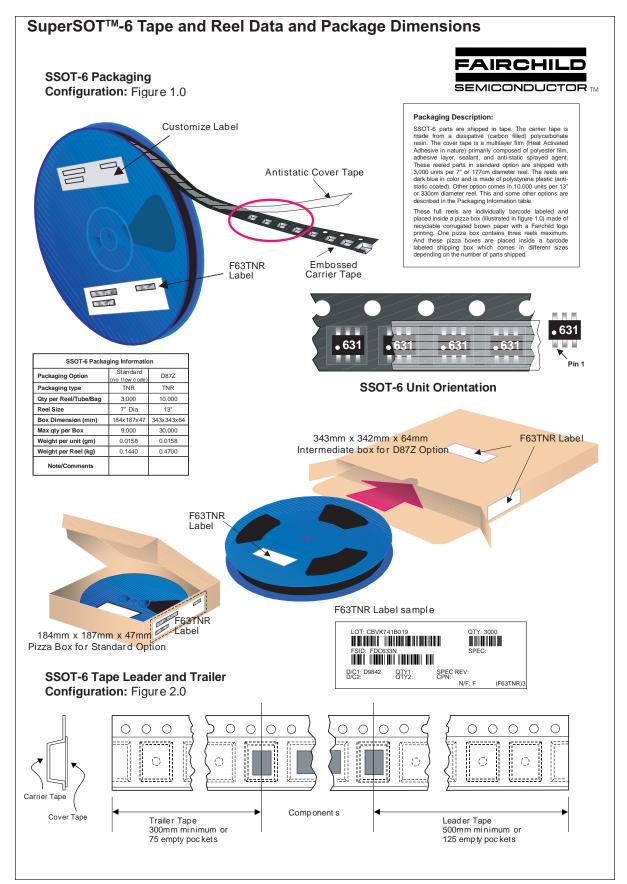


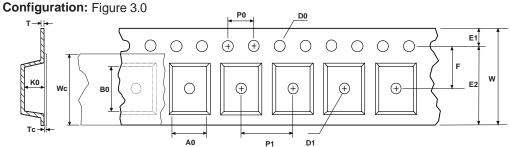
Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient themal response will change depending on the circuit board design.





SSOT-6 Embossed Carrier Tape



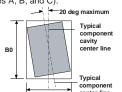


Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
SSOT-6 (8mm)	3.23 +/-0.10	3.18 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

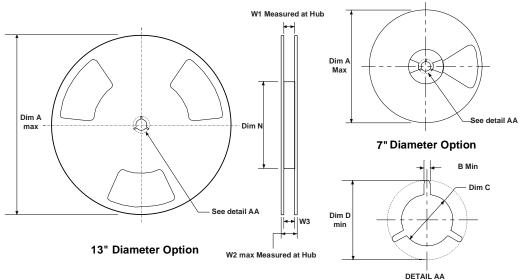


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

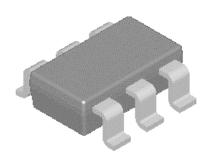
SSOT-6 Reel Configuration: Figure 4.0

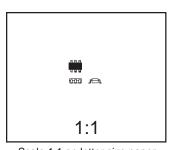


Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9

SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued

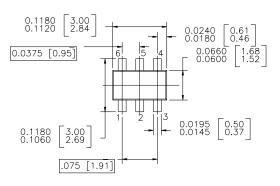
SuperSOT -6 (FS PKG Code 31, 33)

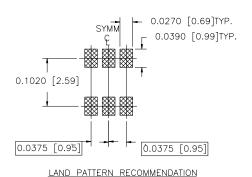




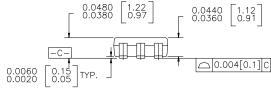
Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

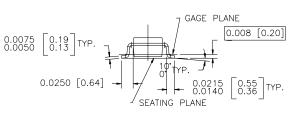
Part Weight per unit (gram): 0.0158





CONTROLLING DIMENSION IS INCH VALUES IN [] ARE MILLIMETERS





NOTES: UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH: 150 MICROINCHES 93.81 MICROMETERS) MINIMUM TIN / LEAD (SOLDER) ON COPPER.

 $2.0\ \mathsf{NO}\ \mathsf{JEDEC}\ \mathsf{REGISTRATION}\ \mathsf{AS}\ \mathsf{OF}\ \mathsf{JULY}\ 1996$

SUPER SOT 6 LEADS

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